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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Kikuta, K.

Serial No.: 09/584,739

Group Art Unit: 2814

Filing Date: June 1, 2000

Examiner: Unknown

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Assistant Commissioner of Patents  
Washington, D.C. 20231

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SUBMISSION OF FORMAL DRAWINGS

Sir:

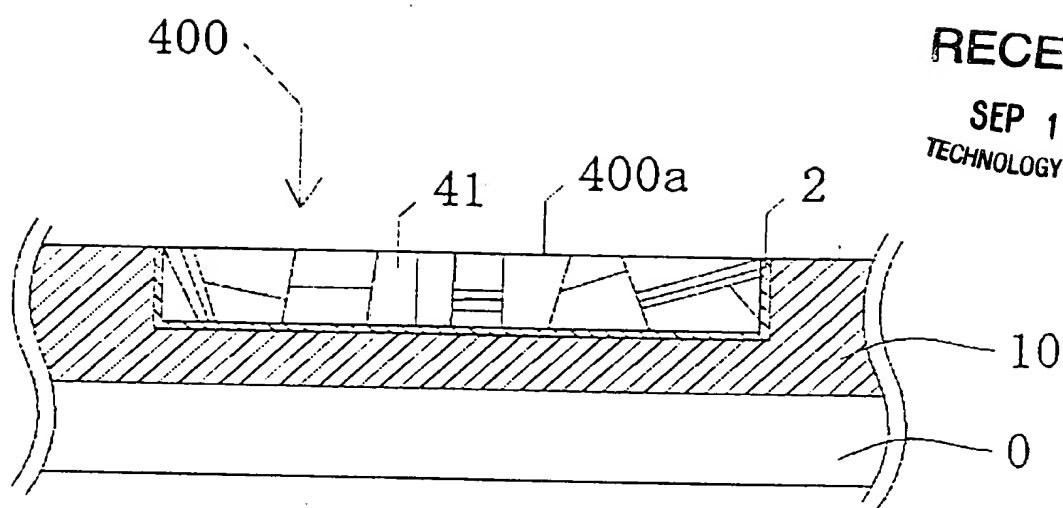
Submitted herewith are twenty-one (21) sheets of formal drawings comprising figures 1A - 6D for the above-identified patent application. Please substitute these formal drawings for the drawings which were filed with the application.

Respectfully submitted,

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FIG. 1A prior art



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FIG. 1B prior art

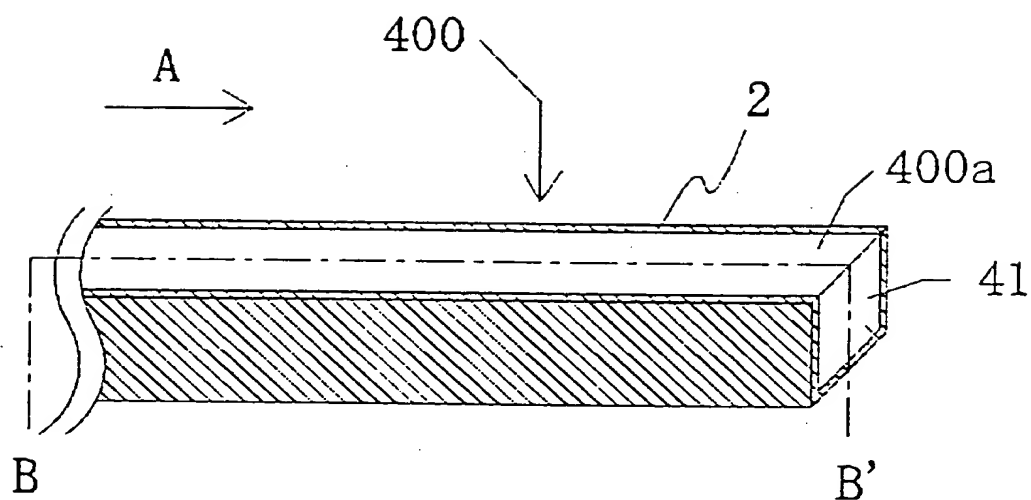


FIG. 1C prior art

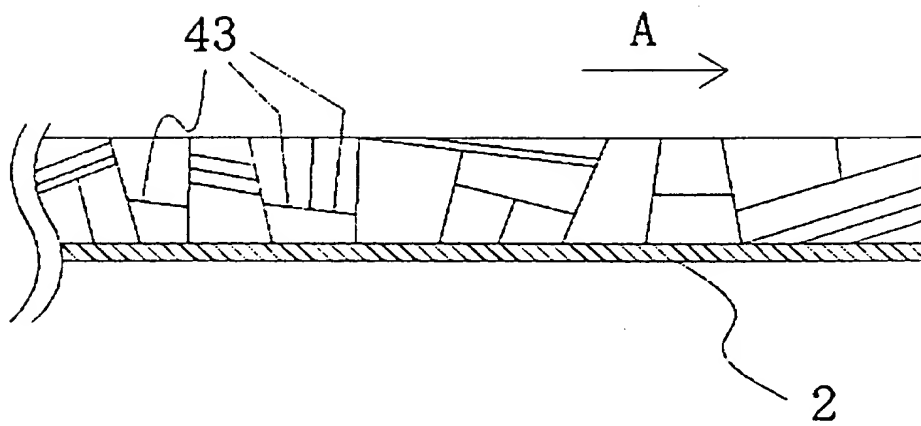


FIG. 2A prior art

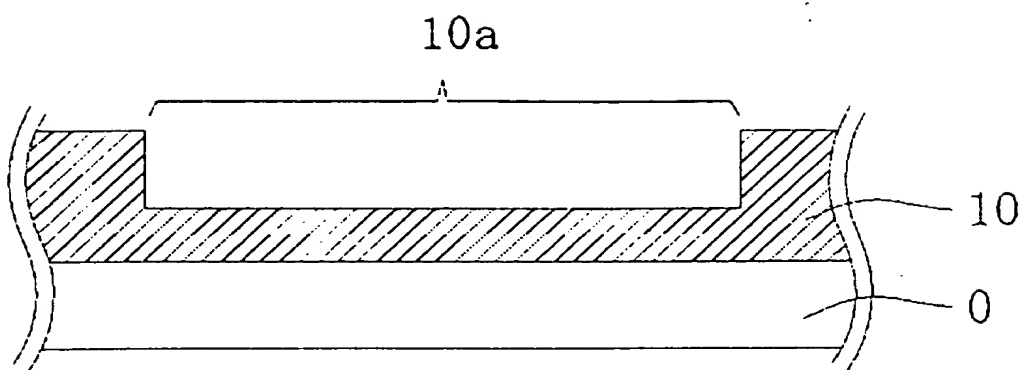


FIG. 2B prior art

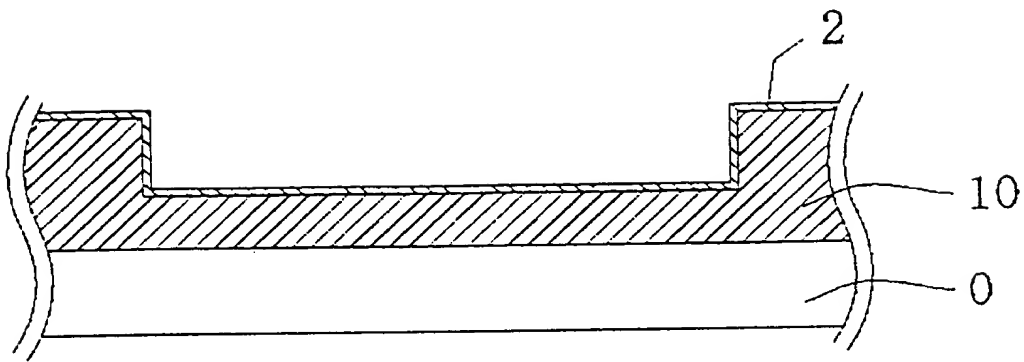


FIG. 2C prior art

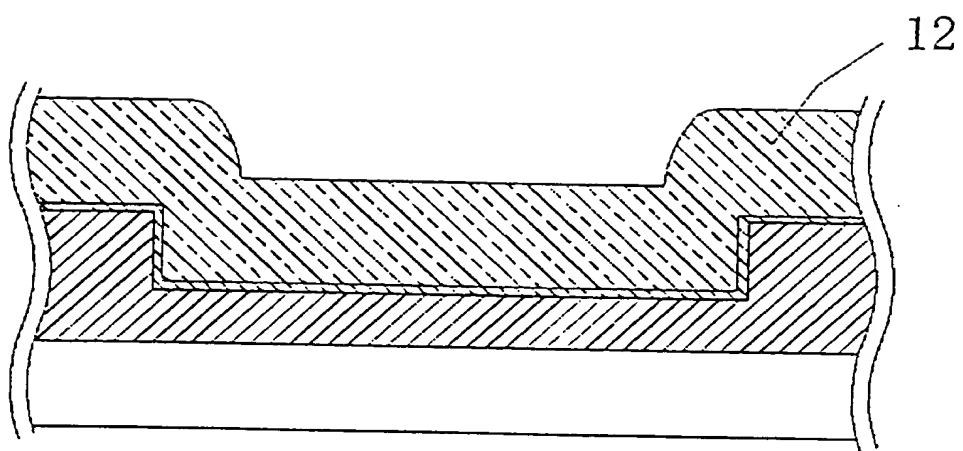


FIG. 2D prior art

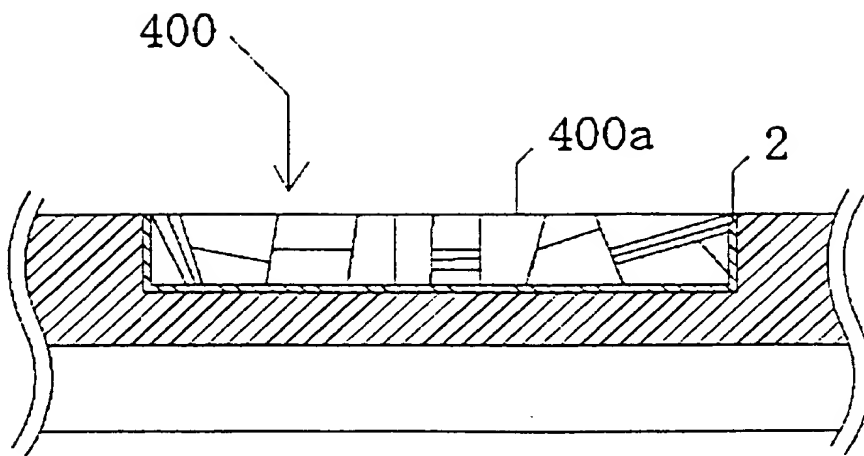




FIG. 3A

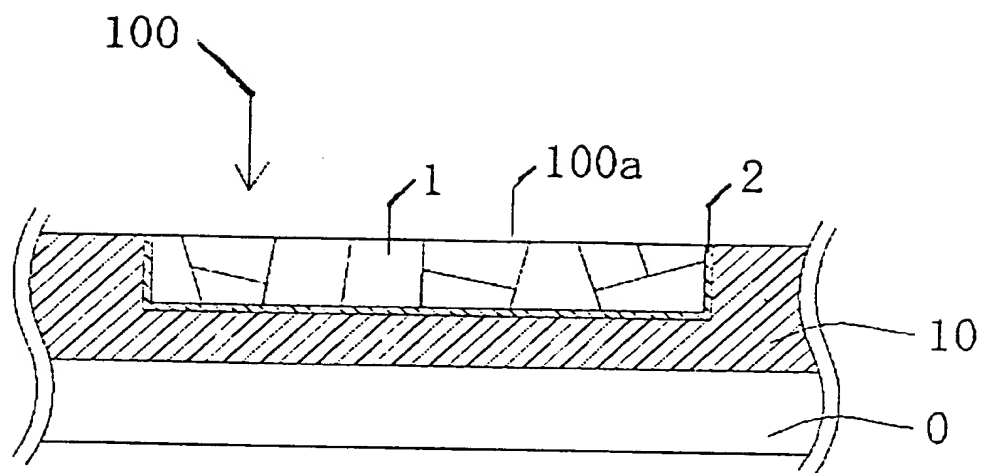


FIG. 3B

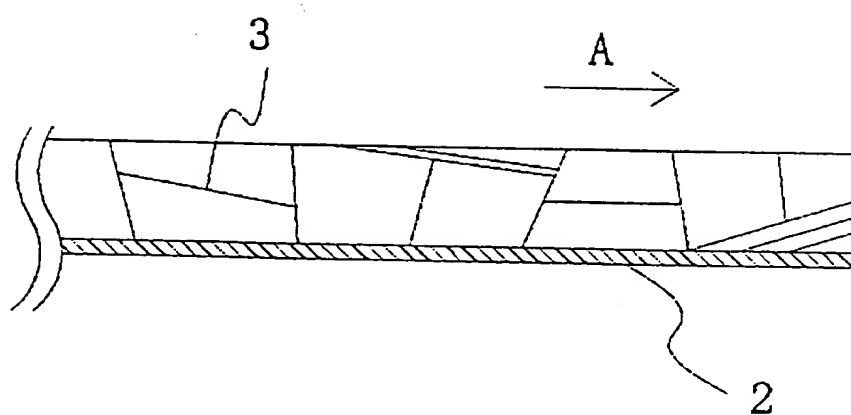


FIG. 3C

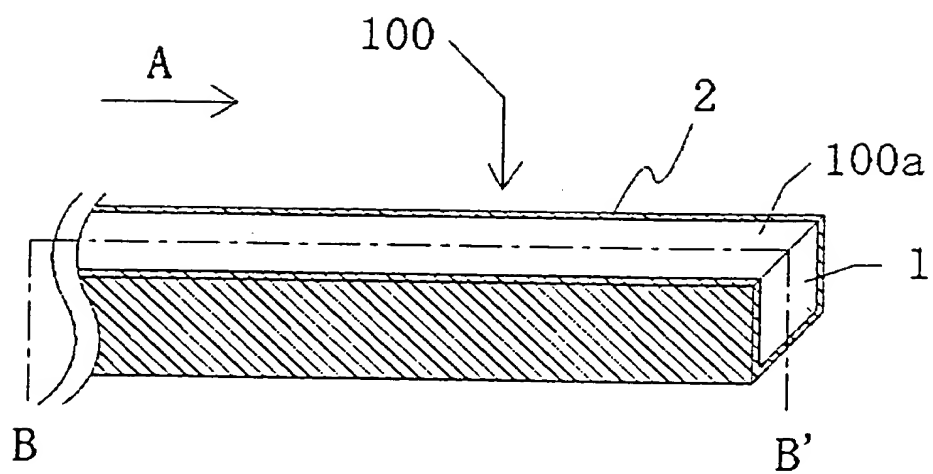


FIG. 3D

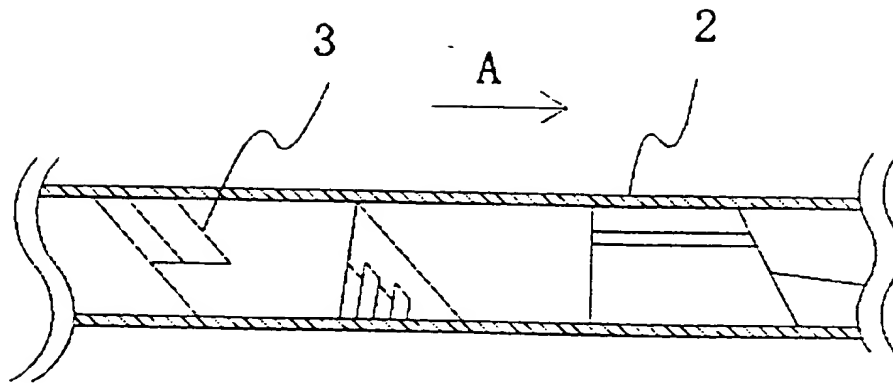
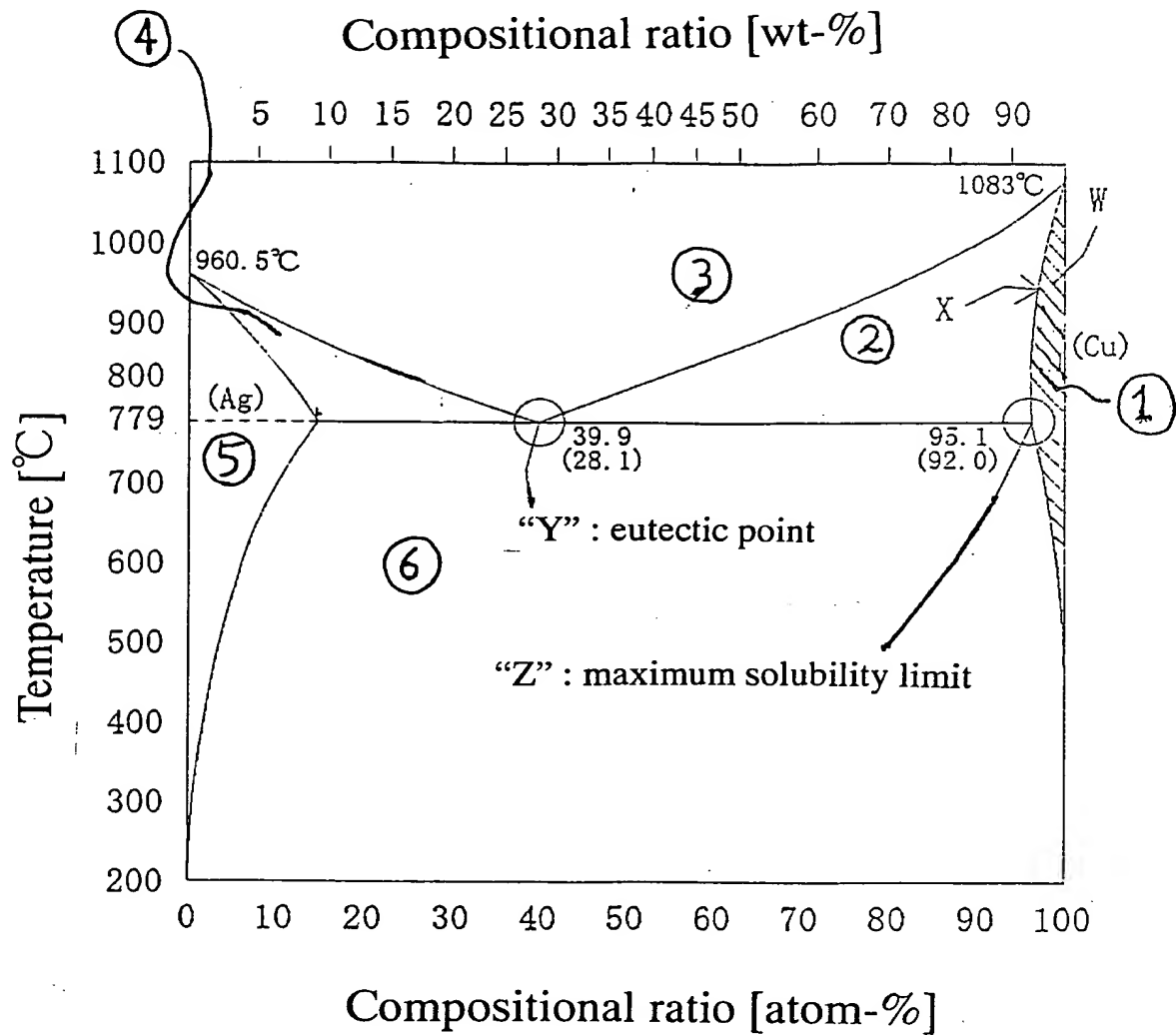


FIG. 4



- ① : a solid phase of Cu.
- ② : co-existence of a liquid phase of Ag and Cu and a solid phase of Cu.
- ③ : a liquid phase of Ag and Cu.
- ④ : co-existence of a liquid phase of Ag and Cu and a solid phase of Ag.
- ⑤ : a solid phase of Ag.
- ⑥ : a solid phase of Ag and Cu.

FIG. 5A

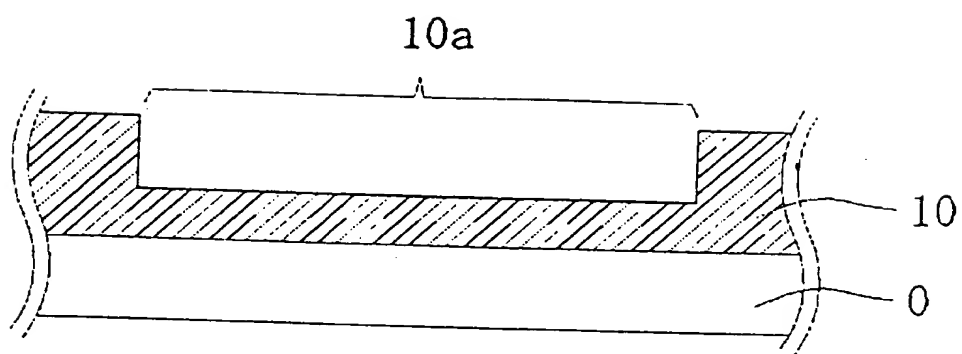


FIG. 5B

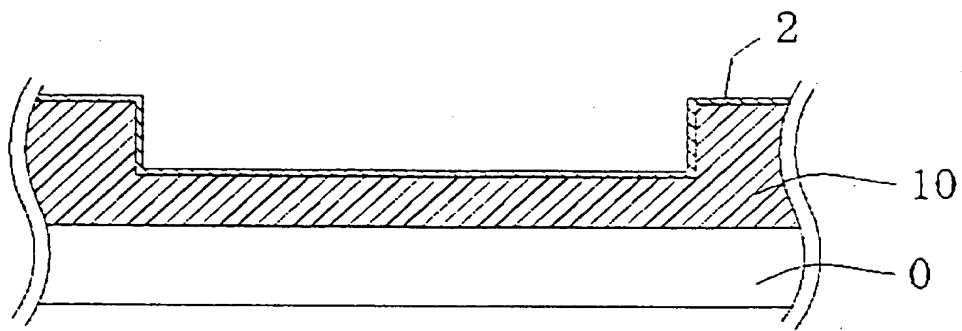


FIG. 5C

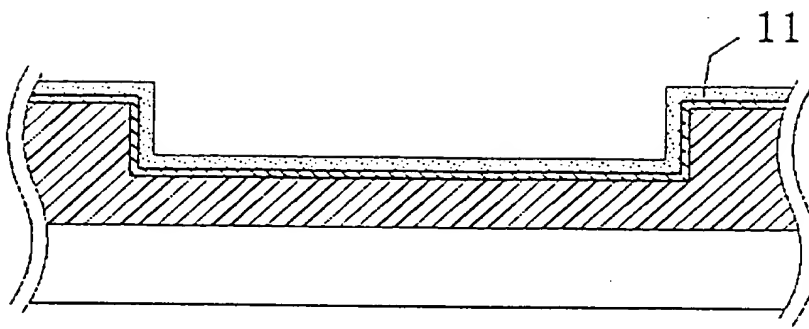




FIG. 5D

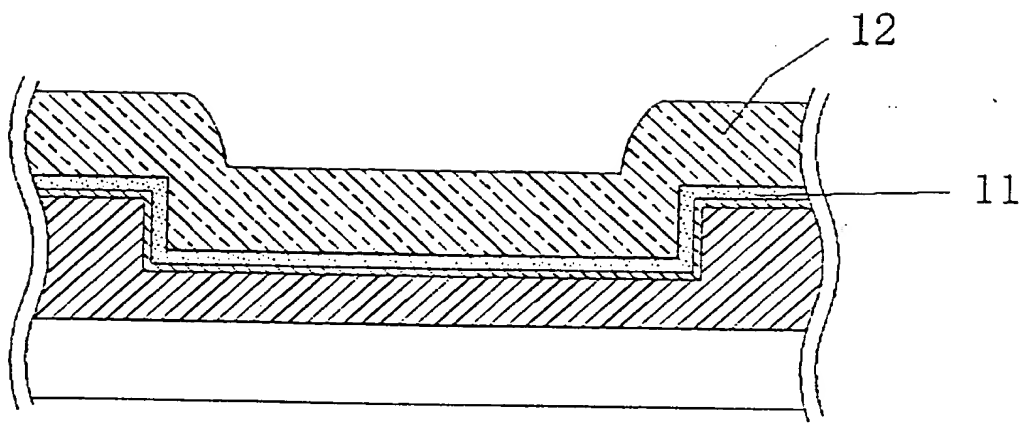


FIG. 5E

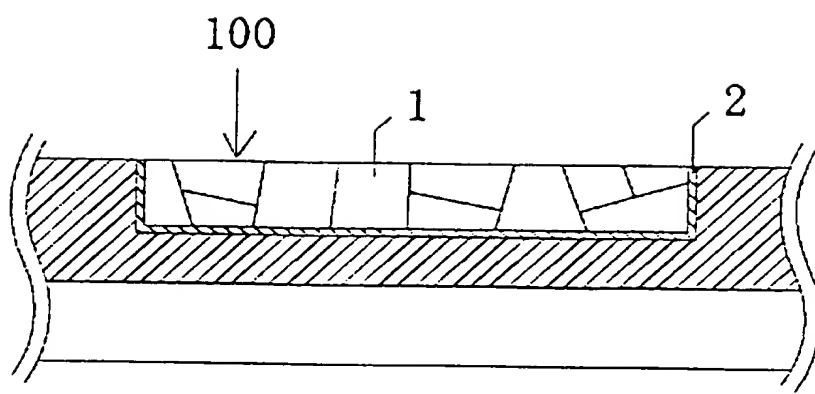


FIG. 6A

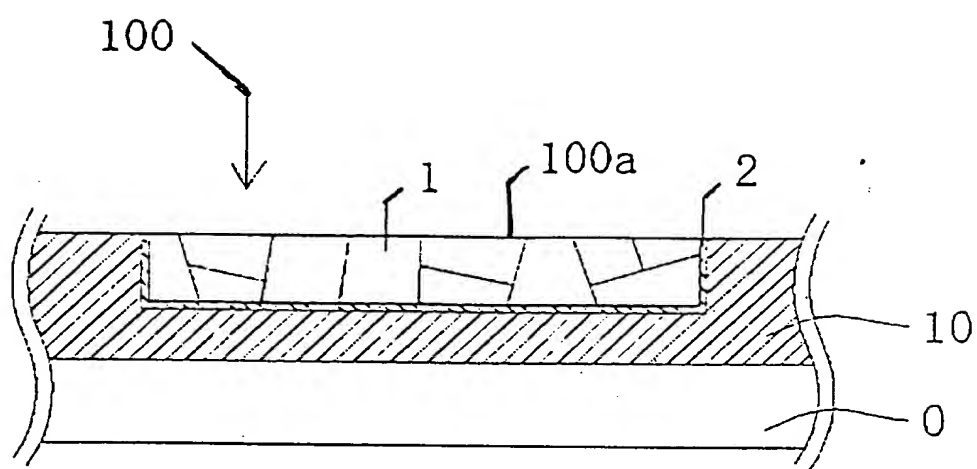


FIG. 6B

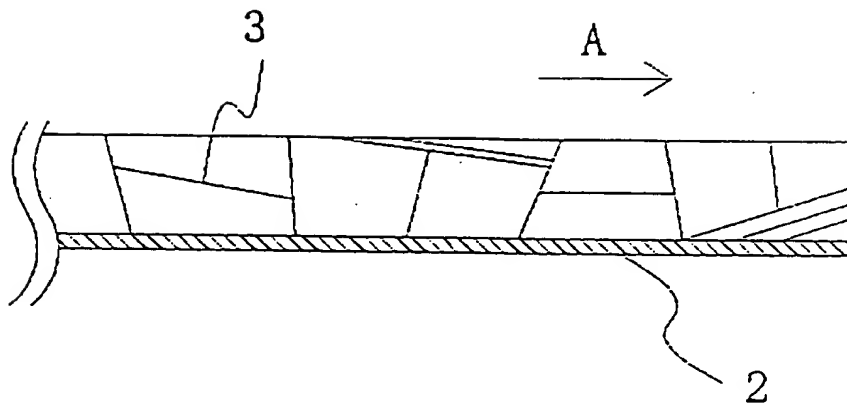


FIG. 6C

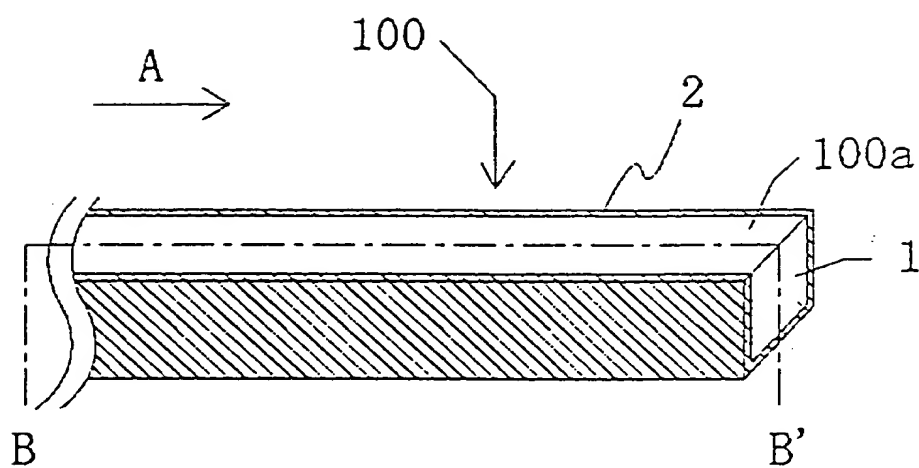


FIG. 6D

